

Final Product/Process Change Notification Document #:FPCN25253XA

Issue Date:17 Apr 2024

Title of Change:	DPAK case outline 369AA/D - Assembly and Test Sites Qualification in Good-Ark, China.		
Proposed First Ship date:	24 Jul 2024 or earlier if approved by customer		
Contact Information:	Contact your local onsemi Sales Office or MuhammadNorakmal.Jani@onsemi.com		
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Additional Reliability Data:	Contact your local onsemi Sales Office or <u>AbdulRasyid.Ruslan@onsemi.com</u>		
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com		
Marking of Parts/ Traceability of Change:	Changed material can be identified by assembly plant code		
Change Category:	Assembly Change, Test Change		
Change Sub-Category(s):	Manufacturing Site Transfer, Material Change		
Sites Affected:	•		
onsemi Sites		External Foundry/Subcon Sites	
None		Good-Ark, China	

Description and Purpose:

This Final Notification announces to customers the qualification of new assembly and test site of DPAK packaged (Case Outline 369AA/D) products to Suzhou Good-Ark Electronics, China for capacity expansion.

	Before Change	After Change		
Assembly & Final Test Site	onsemi Seremban, Malaysia	onsemi Seremban, Malaysia	Good-Ark, China	
Die Attach	Pb95Sn5	Pb95Sn5	Pb92.5Sn5Ag2.5	
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Reliability Data Summary:

QV DEVICE NAME: MJD45H11-1G RMS: S86768, S93944, S96725 PACKAGE: DPAK 369D

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs	0/231
Intermittent Operating Life	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	0/231
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C, mounted form air to air	1000 cyc	0/231
High Temperature High Humidity Reverse Bias	JESD22-A110	85°C, 85% RH, bias	1008 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
Resistance to Solder Heat	JESD22- B106	Ta = 265°C, 10 sec		0/90
Solderability	JSTD002	Ta = 245°C, 5 sec		0/45
Physical Dimension	JESD22-B120			0/90

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle	
MJD112-1G	MJD45H11-1G	
MJD44H11-1G	MJD45H11-1G	
MJD45H11-1G	MJD45H11-1G	

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Appendix A: Changed Products

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DIKG: DIGI-KEY

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
MJD112-1G		MJD45H11-1G	#NONE	
MJD45H11-1G		MJD45H11-1G	#NONE	
MJD44H11-1G		MJD45H11-1G	#NONE	